

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-16. (Canceled)

17. (Currently Amended) A universal packaging system for back-end manufacturing of ICs comprising:

a front-of-line portion for receiving a die-strip and for processing said die-strip using a first plurality of processes that function independently of the die size of said die-strip;

a computer control system comprising a memory resident database for storing said die size of said die-strip;

a first part of an end-of-line portion for receiving said die-strip from said front-of-line portion and for processing said die-strip through a second plurality of processes that function independently of said die size; and

a sawing process for receiving said die-strip from said first part and for sawing said die-strip into individual devices based on said die size as communicated from said database, wherein each of said first and second plurality of processes and said sawing process are adapted to process said individual die-strip at a time in a pipeline manner, and wherein said die-strip includes a single substrate strip adapted for attaching a plurality of dice thereto.

18. (Original) A system as described in Claim 17 further comprising a sorting process for receiving said individual devices from said sawing process and for sorting said individual devices, said sawing and sorting processes being a second part of said end-of-line portion.

19. (Currently Amended) A system as described in Claim 18 wherein said computer control system controls said front-of-line portion, said first part of said end-of line portion, said ~~cutting~~ sawing process and said sorting process.

20. (Original) A system as described in Claim 17 wherein said second plurality of processes of said end-of-line portion comprise an automated in-line cure process that functions independently of said die size.

21. (Original) A system as described in Claim 20 wherein said second plurality of processes of said end-of-line portion further comprise an automated in-line solder ball attachment process that functions independently of said die size.

22. (Original) A system as described in Claim 21 wherein said in-line solder ball attachment process is utilized on both plastic and copper.

23. (Currently Amended) A system as described in Claim 17 wherein said ~~cutting~~ sawing process is an integrated in-line sawing process of said end-of-line portion.

24. (Original) A system as described in Claim 17 wherein said first plurality of processes of said front-of-line portion comprise:

- an in-line die-attachment process that functions independently of said die size;

- an in-line cure process coupled to said in-line die-attachment process, said in-line cure process functioning independently of said die size;

- a first in-line plasma process coupled to said in-line cure process, said first in-line plasma process functioning independently of said die size;

- an in-line bond process coupled to said first in-line plasma process, said in-line bond process functioning independently of said die size; and

- a second in-line plasma process coupled to said in-line bond process, said second in-line plasma process functioning independently of said die size.

25. (Original) A system as described in Claim 17 further comprising:

- a test process coupled to said end-of-line portion for electronically testing said individual devices; and

- a finish assembly portion which produces taped and reeled products.

26. (Currently Amended) A universal packaging system for back-end manufacturing of ICs comprising:

a front-of-line portion for receiving a die-strip and for processing said die-strip using a first plurality of in-line processes that function independently of the die size of said die-strip;

a computer control system comprising a memory resident database for storing said die size of said die-strip;

a first part of an end-of-line portion for receiving and processing said die-strip after said front-of-line portion through a second plurality of in-line processes that function independently of the die size of said die-strip, said second plurality of in-line processes including an in-line mold process and an in-line solder ball attachment process for processing said die-strip after said front-of-line portion, said in-line mold process and said in-line solder ball attachment process functioning independently of said die size; and

a sawing process for receiving from said first part said die-strip and sawing said die-strip into individual devices based on said die size as communicated from said database, wherein each of said first and second plurality of in-line processes and said sawing process are adapted to process said individual die-strip at a time in a pipeline manner, and wherein said die-strip includes a single substrate strip adapted for attaching a plurality of dice thereto.

27. (Original) A system as described in Claim 26 further comprising:

a sorting process for receiving said individual devices from said sawing process and for sorting said individual devices.

28. (Currently Amended) A system as described in Claim 26 wherein said first plurality of in-line processes of said front-of-line portion comprise:

an die-attachment process that functions independently of said die size;
an cure process coupled to said die-attachment process, said cure process functioning independently of said die size;
a first plasma process coupled to said cure process, said first plasma process functioning independently of said die size;
an bond process coupled to said first plasma process, said bond process functioning independently of said die size; and
a second plasma process coupled to said bond process, said second plasma process functioning independently of said die size.

29. (Original) A system as described in Claim 27 further comprising:
a test process coupled to said sorting process and for electronically testing said individual devices; and
a finish assembly portion which produces taped and reeled products.